

FUNCTIONAL BLOCKS





PIN ASSIGNMENTS



FIGURE 2: Pin Assignments for 16-contact LGA



PIN DESCRIPTIONS

TABLE 1: Pin Description

Symbol	Pin No.	Pin Name	Туре	Function
GND	0	Ground		Ground Pad
NC	1	No Connection		Unconnected Pin
RF _{IN} _LB	2		Ι	50 Ω Matched RF Input for Low Band, AC coupled
RF _{IN} _HB	3		Ι	50 Ω Matched RF Input for High Band, AC coupled
NC	4	No Connection		Unconnected Pin
V _{REG} _HB	5	Power Supply	PWR	Analog current control for High Band
NC	6	No Connection		Unconnected Pin
V _{CC} _HB	7	Power Supply	PWR	V _{CC} Power Supply for High Band
D _{ET} _HB	8		0	Detector Voltage Output for High Band
NC	9	No Connection		Unconnected Pin
RF _{OUT} _HB	10	Power Supply	O/PWR	50 Ω Matched RF output for High Band
RF _{OUT} _LB	11	Power Supply	O/PWR	50 Ω Matched RF output for Low Band
NC	12	No Connection		Unconnected Pin
D _{ET} _LB	13		0	Detector Voltage Output for Low Band
V _{CC} _LB	14	Power Supply	PWR	V _{CC} Power Supply for Low Band
NC	15	No Connection		Unconnected Pin
V _{REG} _LB	16	Power Supply	PWR	Analog current control for Low Band

T1.0 1318



ELECTRICAL SPECIFICATIONS

The AC and DC specifications for the power amplifier interface signals. Refer to Tables 2 and 4 for the DC voltage and current specifications. Refer to Figures 3 through 22 for the RF performance.

Absolute Maximum Stress Ratings Applied conditions greater than those listed under "Absolute Maximum Stress Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions or conditions greater than those defined in the operational sections of this data sheet is not implied. Exposure to absolute maximum stress rating conditions may affect device reliability.

Supply Voltage (V _{CC})	0.3V to +3.6V
Reference Voltage (V _{REF})	0.3V to +3.3V
DC supply current (I _{CC})	400 mA
Operating Temperature (T _A)	40°C to +85°C
Storage Temperature (T _{STG})	
Maximum Junction Temperature (T _J)	



For 802.11b/g Operation

TABLE 2: DC Electrical Characteristics

Symbol	Parameter	Min.	Тур	Max.	Unit
V _{CC}	Supply Voltage	3.0	3.3	3.6	V
I _{CC}	Supply Current				
	for 802.11g, 19 dBm		160		mA
	for 802.11b, 23.5 dBm		235		mA
I _{REG}	Analog control current at On state			2	mA
V _{REG}	Reference Voltage		2.95		V

T2.0 1318

TABLE 3: AC Electrical Characteristics for Configuration

Symbol	Parameter	Min.	Тур	Max.	Unit
F _{L-U}	Frequency range	2.4		2.5	GHz
G	Small signal gain	28	29		dB
G _{VAR1}	Gain variation over temperature 0°C – 85°C	-1		1	dB
G _{VAR2}	Gain flatness over any 50 MHz bandwidth	-0.3		0.3	dB
ACPR	Meet 11b spectrum mask	22	23		dBm
	Meet 11g OFDM 54 Mbps spectrum mask	22	23		dBm
Added EVM	P _{OUT} = 19 dBm with 54Mbps			-28	dB
	11g OFDM signal when operating at 3.3V Vcc			4	%
2f, 3f, 4f, 5f	Harmonics at P _{OUT} = 20 dBm			-50	dBc
	Spurious non-harmonics at $P_{OUT} = 20 \text{ dBm}$			-60	dBc
	In/Out return loss at 50 Ω nominal impedance	6			dB

T3.0 1318



For 802.11a Operation

TABLE 4: DC Electrical Characteristics

Symbol	Parameter	Min.	Тур	Max.	Unit
V _{CC}	Supply Voltage	3	3.3	3.6	V
I _{CC}	Supply Current				
	for 802.11a, 18 dBm		270		mA
I _{REG}	Analog control current at On state			2	μA
V _{REG}	Reference Voltage		2.95		V

T4.1 1318

TABLE 5: AC Electrical Characteristics for Configuration

Symbol	Parameter	Min.	Тур	Max.	Unit
F _{L-U}	Frequency range	4.92		5.805	GHz
G	Small signal gain across 4.9- 5.8 GHz	26			dB
G _{VAR1}	Gain variation over temperature 0°C – 85°C	-1		1	dB
G _{VAR2}	Gain flatness over any 100 MHz bandwidth	-0.5		0.5	dB
ACPR	Meet 11a OFDM 54 Mbps spectrum mask	22	22.5		dBm
Added EVM	P _{OUT} = 18 dBm with 54Mbps			-28	dB
	11aOFDM signal when operating at 3.3V Vcc			4	%
2f, 3f, 4f, 5f	Harmonics at 20 dBm			-45	dBc

T5.1 1318



Typical Low Band Performance for 802.11b/g

Test Conditions: V_{CC} = 3.3V, T_A = 25°C, V_{REF} = 2.95V unless otherwise noted



FIGURE 3: Low Band S-Parameters





Test Conditions: V_{CC} = 3.3 V, V_{REF} = 2.95 V, 54 Mbps 802.11g OFDM signal

FIGURE 4: Low Band Output Power versus Input Power







FIGURE 6: Low Band Supply Current versus Output Power









FIGURE 8: Low Band EMV versus Output Power









Test Conditions: V_{CC} = 3.3V, V_{REF} = 2.95V, T_A = 25°C, 1 Mbps 802.11b CCK Signal

FIGURE 10: Low Band 802.11b Spectrum Mask at 23.5 dBm with DC Current of 235 mA



Low Band Power Detector Characteristics

Test Conditions: V_{CC} = 3.3V, V_{REF} = 2.95V, T_A = 25°C, 54 Mbps 802.11g OFDM Signal



FIGURE 11: Low Band Detector Voltage versus Output Power



Typical High Band Performance for 802.11a

Test Conditions: V_{CC} = 3.3V, T_A = 25°C, V_{REF} = 2.95V unless otherwise noted



FIGURE 12: High Band S-Parameters







FIGURE 13: High Band Output Power versus Input Power







FIGURE 15: High Band Supply Current versus Output Power









FIGURE 17: High Band EVM versus Output Power



DC Current at 370 mA





FIGURE 19: High Band 802.11a Spectrum Mask at 5.18 GHz at Output Power 22.5 dBm with DC Current at 355 mA



FIGURE 20: High Band 802.11a Spectrum Mask at 5.32 GHz at Output Power 23 dBm with DC Current at 360 mA





FIGURE 21: High Band 802.11a Spectrum Mask at 5.805 GHz at Output Power 23 dBm with DC Current at 350 mA



High Band Power Detector characteristics

Test Conditions: V_{CC} = 3.3V, V_{REF} = 2.95V, T_A = 25°C, 54 Mbps 802.11a OFDM Signal



FIGURE 22: High Band Detector Voltage versus Output Power





FIGURE 23: Typical Application Circuit



PRODUCT ORDERING INFORMATION



1. Environmental suffix "F" denotes non-Pb solder. SST non-Pb solder devices are "RoHS Compliant".

Valid combinations for SST13LP05 SST13LP05-MLCF

SST13LP05 Evaluation Kits

SST13LP05-MLCF-K

Note: Consult your SST sales representative to confirm availability of valid combinations.





FIGURE 24: 16-Contact Low-profile, Fine-pitch, Land Grid Array (LFLGA) SST Package Code: MLC

TABLE 6: Revision History

Revision	Description			
00	•	Initial release of data sheet.	Dec 2006	
01	•	Updated document status from Preliminary Specification to Data Sheet	Apr 2008	
02	•	Updated "Contact Information" on page 24.	Feb 2009	



CONTACT INFORMATION

Marketing

SST Communications Corp.

5340 Alla Road, Ste. 210 Los Angeles, CA 90066 Tel: 310-577-3600 Fax: 310-577-3605

Sales and Marketing Offices

NORTH AMERICA

Silicon Storage Technology, Inc.

1171 Sonora Court Sunnyvale, CA 94086-5308 Tel: 408-735-9110 Fax: 408-735-9036

EUROPE

Silicon Storage Technology Ltd.

Mark House 9-11 Queens Road Hersham, Surrey KT12 5LU UK Tel: 44 (0) 1932-238133 Fax: 44 (0) 1932-230567

JAPAN

SST Japan

NOF Tameike Bldg, 9F 1-1-14 Akasaka, Minato-ku Tokyo, Japan 107-0052 Tel: 81-3-5575-5515 Fax:81-3-5575-5516

ASIA PACIFIC NORTH

SST Macao

Room N, 6th Floor, Macao Finance Center, No. 202A-246, Rua de Pequim, Macau Tel: 853-2870-6022 Fax: 853-2870-6023

ASIA PACIFIC SOUTH

SST Communications Co.

16F-6, No. 75, Sec.1, Sintai 5th Rd Sijhih City, Taipei County 22101 Taiwan, R.O.C. Tel: 886-2-8698-1198 Fax: 886-2-8698-1190

KOREA

SST Korea

6F, Heungkuk Life Insurance Bldg 6-7 Sunae-Dong, Bundang-Gu, Sungnam-Si Kyungki-Do, Korea, 463-020 Tel: 82-31-715-9138 Fax: 82-31-715-9137

Silicon Storage Technology, Inc. • 1171 Sonora Court • Sunnyvale, CA 94086 • Telephone 408-735-9110 • Fax 408-735-9036 www.SuperFlash.com or www.sst.com